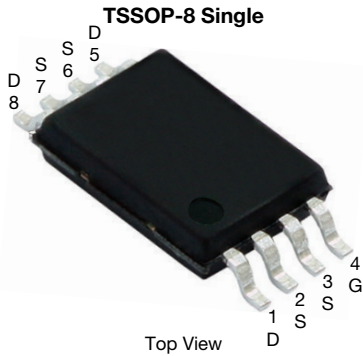




**THE DATASHEET OF
SI6423ADQ-T1-GE3**



P-Channel 20 V (D-S) MOSFET



FEATURES

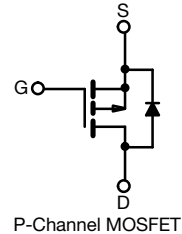
- TrenchFET® power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Load switch
- Battery switch
- Power management



PRODUCT SUMMARY	
V _{DS} (V)	-20
R _{DS(on)} max. (Ω) at V _{GS} = -4.5 V	0.0098
R _{DS(on)} max. (Ω) at V _{GS} = -2.5 V	0.0130
R _{DS(on)} max. (Ω) at V _{GS} = -1.8 V	0.0227
Q _g typ. (nC)	63
I _D (A) ^d	-12.5
Configuration	Single

ORDERING INFORMATION	
Package	TSSOP-8
Lead (Pb)-free and halogen-free	Si6423ADQ-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-20	V
Gate-source voltage		V _{GS}	± 8	
Continuous drain current (T _J = 150 °C) ^a	T _C = 25 °C	I _D	-12.5	A
	T _C = 70 °C		-10	
	T _A = 25 °C		-10.3 ^{a, b}	
	T _A = 70 °C		-8.2 ^{a, b}	
Pulsed drain current (t = 300 μs)		I _{DM}	-70	
Continuous source-drain diode current	T _C = 25 °C	I _S	-1.9	
	T _A = 25 °C		-1.3	
Avalanche current	L = 0.1 mH	I _{AS}	-20	
Single pulse avalanche energy		E _{AS}	20	mJ
Maximum power dissipation	T _C = 25 °C	P _D	2.2	W
	T _C = 70 °C		1.4	
	T _A = 25 °C		1.5 ^{a, b}	
	T _A = 70 °C		1.0 ^{a, b}	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^{a, c}	t ≤ 10 s	R _{thJA}	65	83	°C/W
Maximum junction-to-case (drain)	Steady state	R _{thJC}	46	56	

Notes

- Surface mounted on 1" x 1" FR4 board
- t = 10 s
- Maximum under steady state conditions is 120 °C/W
- T_C = 25 °C



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-20	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = -250 μA	-	-11	-	mV/°C
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J		-	2.9	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-0.4	-	-1	V
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V	-	-	-1	μA
		V _{DS} = -20 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10	
On-state drain current ^a	I _{D(on)}	V _{DS} ≤ -5 V, V _{GS} = -10 V	-10	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -4.5 V, I _D = -10 A	-	0.0082	0.0098	Ω
		V _{GS} = -2.5 V, I _D = -8 A	-	0.0108	0.0130	
		V _{GS} = -1.8 V, I _D = -5 A	-	0.0175	0.0227	
Forward transconductance ^a	g _{fs}	V _{DS} = -10 V, I _D = -10 A	-	70	-	S
Dynamic ^b						
Input capacitance	C _{ISS}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	-	5875	-	pF
Output capacitance	C _{OSS}		-	540	-	
Reverse transfer capacitance	C _{rss}		-	555	-	
Total gate charge	Q _g	V _{DS} = -10 V, V _{GS} = -8 V, I _D = -16.7 A	-	112	168	nC
			V _{DS} = -10 V, V _{GS} = -4.5 V, I _D = -16.7 A	-	63	
Gate-source charge	Q _{gs}	V _{DS} = -10 V, V _{GS} = -4.5 V, I _D = -16.7 A	-	8.7	-	
Gate-drain charge	Q _{gd}		-	25.3	-	
Gate resistance	R _g	f = 1 MHz	0.8	3.6	7.2	Ω
Turn-on delay time	t _{d(on)}	V _{DD} = -10 V, R _L = 1 Ω, I _D ≅ -10 A, V _{GEN} = -8 V, R _g = 1 Ω	-	12	24	ns
Rise time	t _r		-	4	8	
Turn-off delay time	t _{d(off)}		-	120	180	
Fall time	t _f		-	36	54	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-18	A
Pulse diode forward current ^a	I _{SM}		-	-	-70	
Body diode voltage	V _{SD}	I _S = -10 A	-	-0.75	-1.2	V
Body diode reverse recovery time	t _{rr}	I _F = -10 A, di/dt = 100 A/μs, T _J = 25 °C	-	45	68	ns
Body diode reverse recovery charge	Q _{rr}		-	38	57	nC
Reverse recovery fall time	t _a		-	18	-	ns
Reverse recovery rise time	t _b		-	27	-	

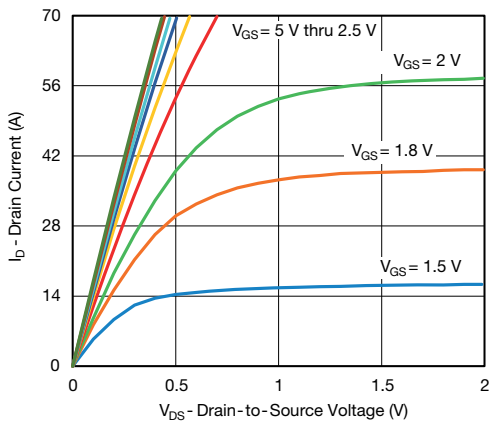
Notes

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %
- b. Guaranteed by design, not subject to production testing

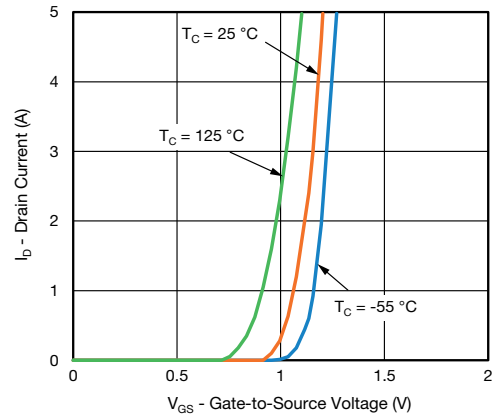
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



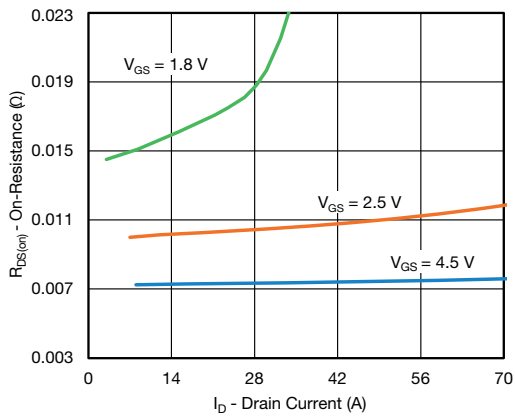
TYPICAL CHARACTERISTICS (T_J = 25 °C, unless otherwise noted)



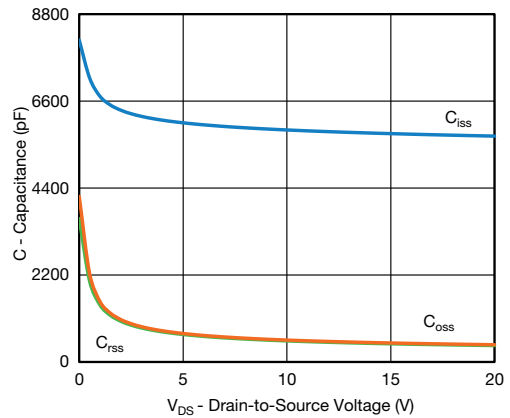
Output Characteristics



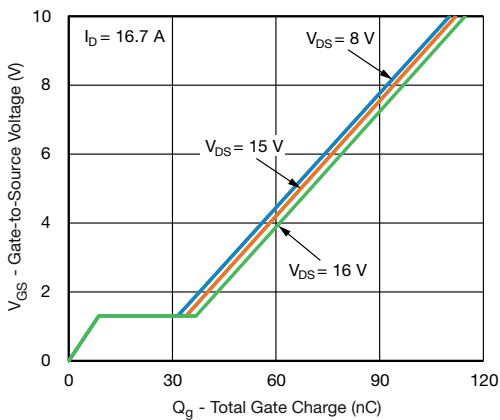
Transfer Characteristics



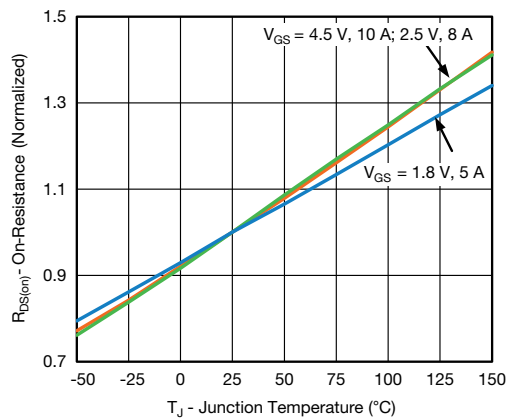
On-Resistance vs. Drain Current



Capacitance

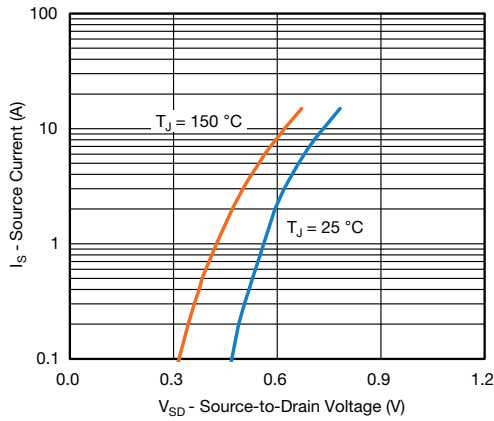


Gate Charge

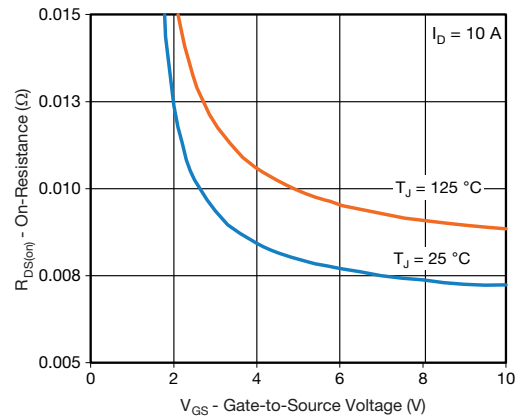


Normalized On-Resistance vs. Junction Temperature

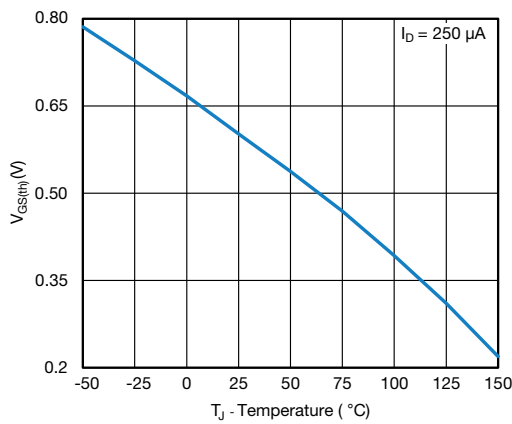
TYPICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)



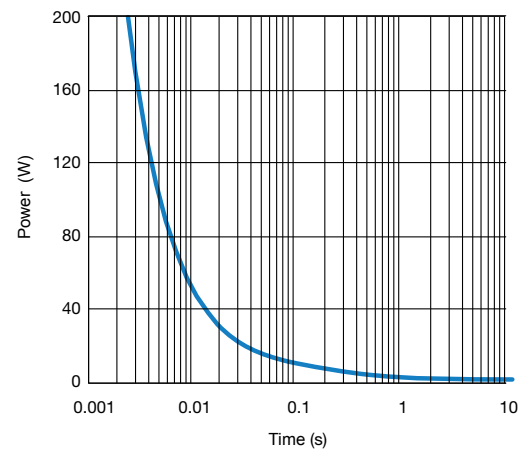
Source-Drain Diode Forward Voltage



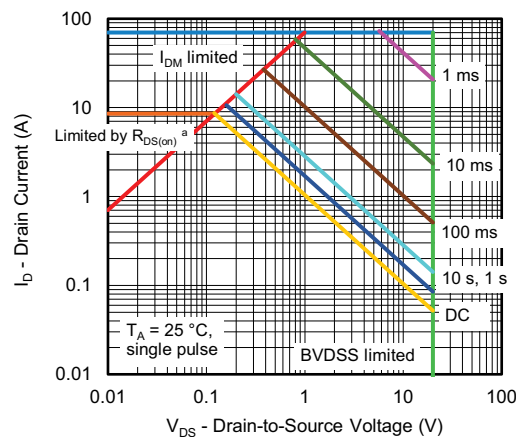
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



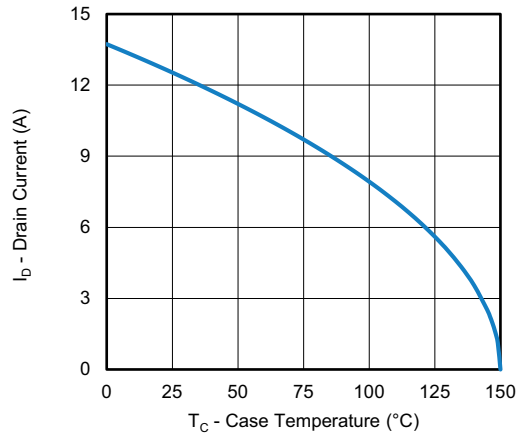
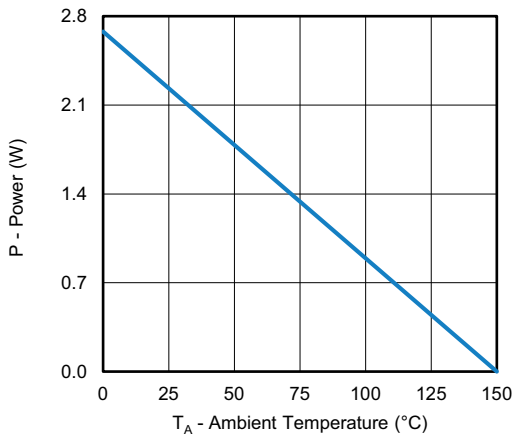
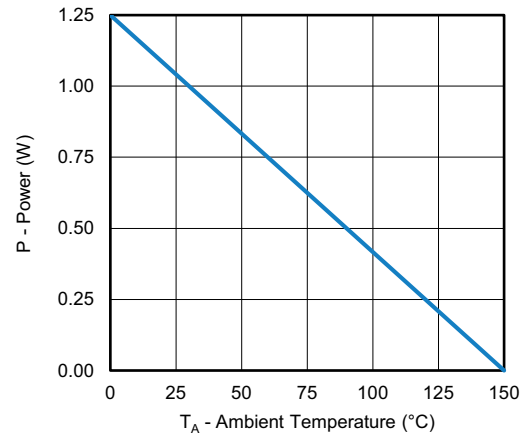
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

Note

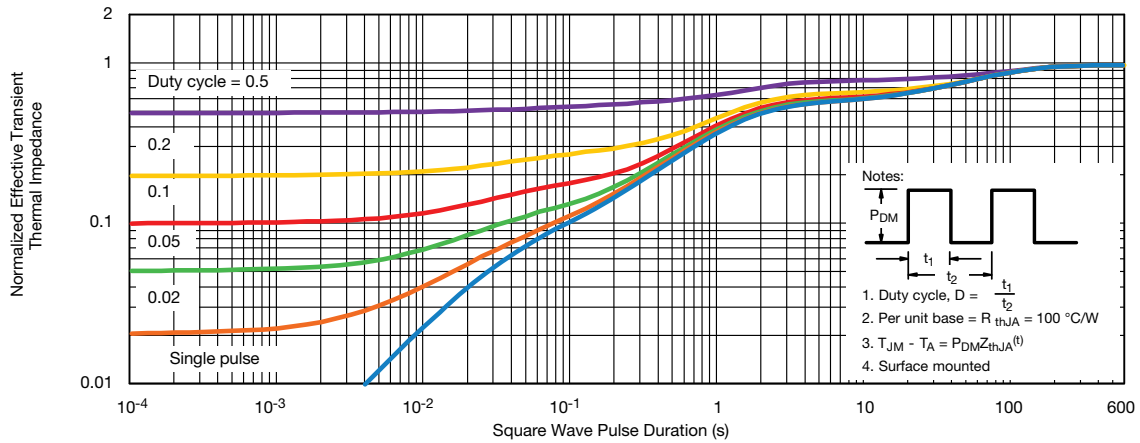
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

TYPICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)

Current Derating ^a

Power, Junction-to-Case

Power, Junction-to-Ambient
Note

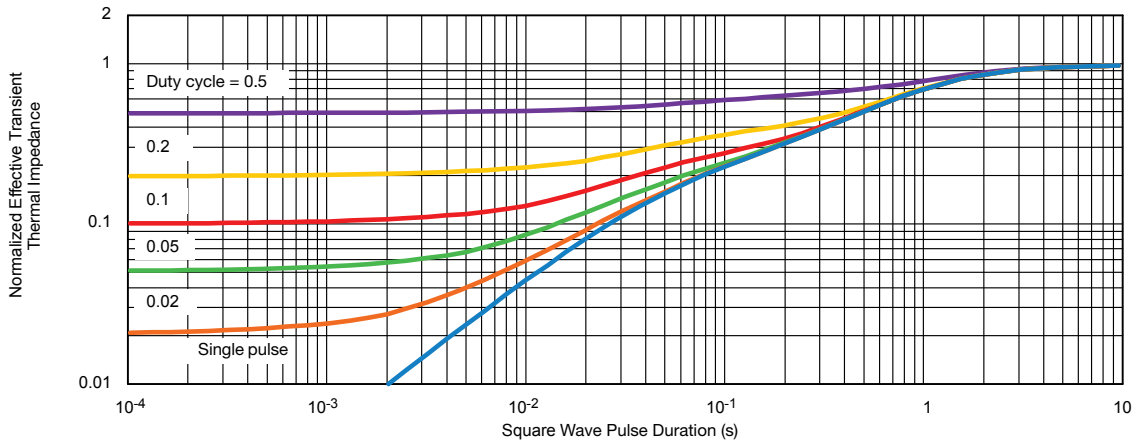
- a. The power dissipation P_D is based on T_J max. = 150 $^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (T_J = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



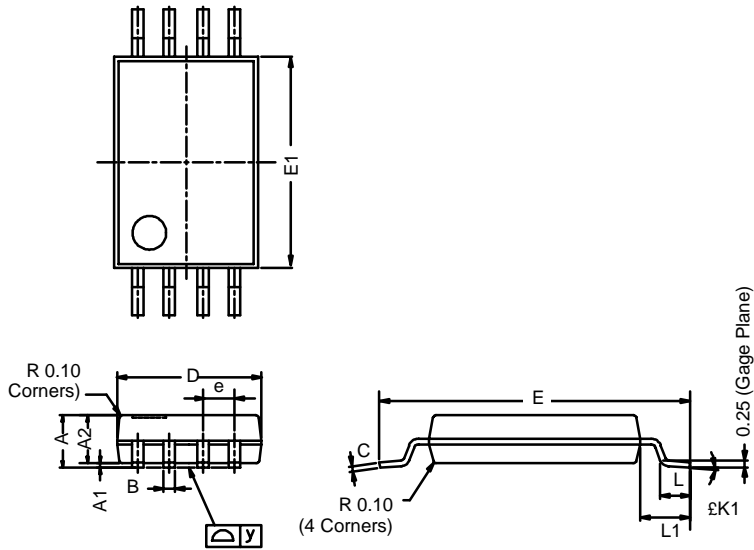
Normalized Thermal Transient Impedance, Junction-to-Case

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TSSOP: 8-LEAD

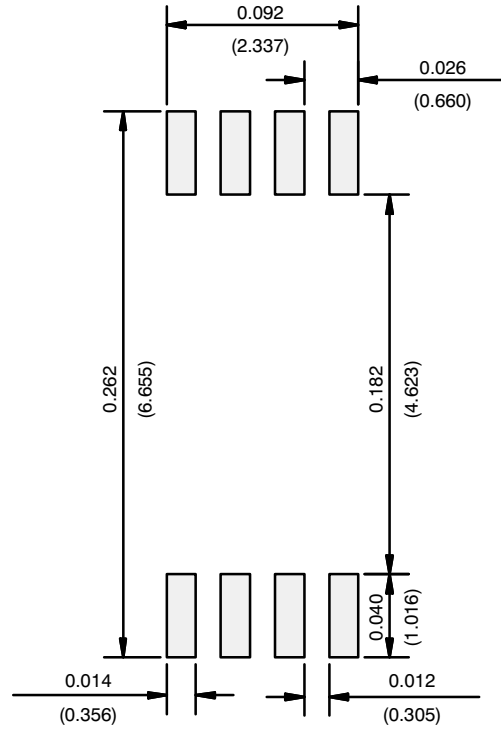
JEDEC Part Number: MO-153



Dim	MILLIMETERS		
	Min	Nom	Max
A	–	–	1.20
A ₁	0.05	0.10	0.15
A ₂	0.80	1.00	1.05
B	0.19	0.28	0.30
C	–	0.127	–
D	2.90	3.00	3.10
E	6.20	6.40	6.60
E ₁	4.30	4.40	4.50
e	–	0.65	–
L	0.45	0.60	0.75
L ₁	0.90	1.00	1.10
Y	–	–	0.10
£K1	0°	3°	6°

ECN: S-03946—Rev. G, 09-Jul-01
DWG: 5844

RECOMMENDED MINIMUM PADS FOR TSSOP-8



Recommended Minimum Pads
Dimensions in Inches/(mm)

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